USN

Sixth Semester B.E. Degree Examination, Dec.2018/Jan.2019 Micro and Smart System Technology

Time: 3 hrs.

Max. Marks: 100

Note: Answer any FIVE full questions, selecting at least TWO full questions from each part.

PART - A

- 1 a. List the difference between Microsystems and Microelectronics. (05 Marks)
 - b. Mention the technical reasons for miniaturization. (05 Marks)
 - c. With neat block diagram explain typical smart system and compare each component with respect to biological system. (10 Marks)
- 2 a. Describe working of silicon capacitive accelerometer.

(08 Marks)

b. Briefly explain operation of portable blood analyzer.

- (06 Marks)
- c. With neat schematic explain material used and principle of operation of comb-drive.

(06 Marks)

- 3 a. Explain Evaporation and sputtering processes in thin film deposition. (10 Marks)
 - b. With the help of neat schematic explain the process steps involved in realizing contilever structure by surface micromachining.

 (10 Marks)
- 4 a. Explain the concept of coupled electro mechanics in details. (10 Marks)
 - b. Discuss the effect of residual stresses and stress gradients. (10 Marks)

PART – B

- 5 a. Using Finite Element method analyze a Rod element and beam element shape functions.
 - (10 Marks)
- b. What is Finite Element method? Explain its procedure using flow chart.
- (10 Marks)
- 6 a. Explain the operation of switched capacitor circuit for capacitance measurement. (10 Marks)
 - b. With necessary mathematical equations, explain, state-space modeling. (10 Marks)
- 7 a. Discuss the special issues in microsystem packaging with packaging parameter. (10 Marks)
 - b. Describe with neat diagram wire bonding and flip chip assembly packaging technologies.

(10 Marks)

- 8 Write a short note on the following:
 - a. Lithography-photolithography
 - b. Thin film deposition
 - c. Pressure sensor
 - d. Active vibration control of a beam.

(20 Marks)

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